GSM3612P

30V N-Channel MOSFETs

Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

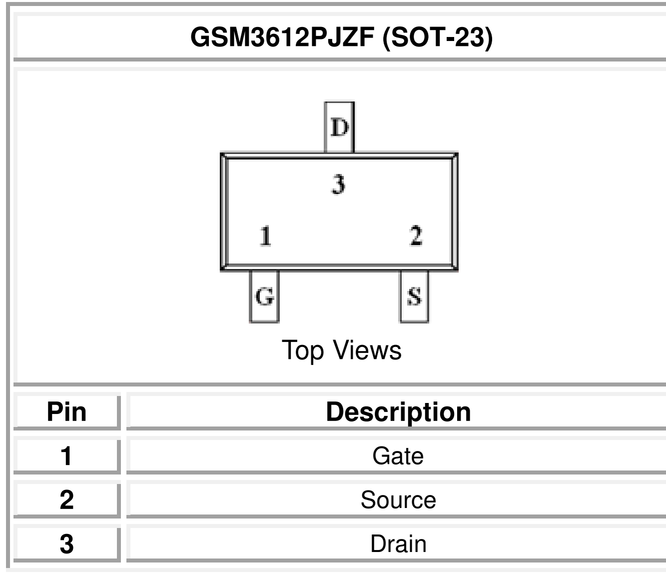
Features

- 30V, 5.3A, $R_{DS(ON)}$=36mΩ@V_{GS}=4.5V
- Improved dv/dt capability
- Fast switching
- Suit for 2.5V Gate Drive Applications
- Green Device Available
- SOT-23 package design

Applications

- Notebook
- Load Switch
- LED applications

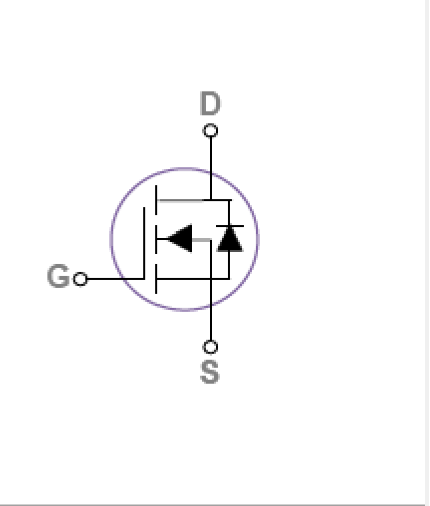
Packages & Pin Assignments



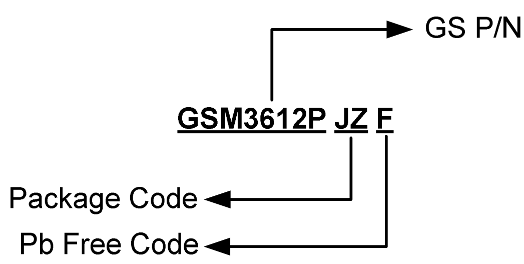
GSM3612PJZF (SOT-23)

Top Views

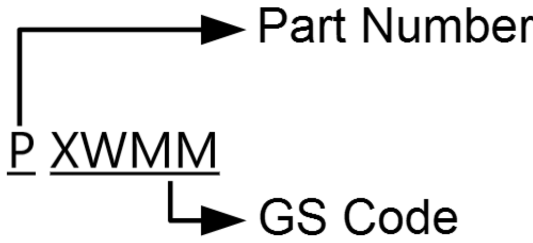
Pin	Description
1	Gate
2	Source
3	Drain



Ordering Information



Marking Information



Part Number	Package	Part Marking	Quantity
GSM3612PJZF	SOT-23	PXWMM	3000pcs

Absolute Maximum Ratings

T_C=25ºC Unless otherwise noted

Symbol	Parameter		Typical	Unit
V_{DS}	Drain-Source Voltage		30	V
V_{GS}	Gate-Source Voltage		±12	V
I_D	Continuous Drain Current	T_C=25℃	5.3	A
		T_C=100℃	3.4	A
I_{DM}	Pulsed Drain Current[1]		21.2	A
P_D	Power Dissipation (Tc=25℃)		1.56	W
	Power Dissipation (Derate above 25℃)		0.012	W/℃
T_J	Operating Junction Temperature Range		-55 to +150	℃
T_{STG}	Storage Temperature Range		-55 to +150	℃
$R_{θJA}$	Thermal Resistance-Junction to Ambient		80	℃/W

Electrical Characteristics

T_J=25℃ Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V,I_D=250uA	30			V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃, I_D=1mA		0.06		V/℃
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS},I_D=250uA	0.4	0.6	0.9	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient	V_{DS}=V_{GS},I_D=250uA		-3		mV/℃
I_{GSS}	Gate Leakage Current	V_{DS}=0V,V_{GS}=±12V			±100	nA
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V,V_{GS}=0V			1	uA
		V_{DS}=24V,V_{GS}=0V, T_J=125℃			10	
I_S	Continuous Source Current	V_G=V_D=0V, Force Current			5.3	A
I_{SM}	Pulsed Source Current				21.2	
$R_{DS(on)}$	Drain-Source On-Resistance	V_{GS}=4.5V,I_D=4A		31	36	mΩ
		V_{GS}=2.5V,I_D=3A		36	45	
g_{FS}	Forward Transconductance	V_{DS}=10V,I_D=3A		7		S
V_{SD}	Diode Forward Voltage	V_{GS}=0V,I_S=1A			1	V
Dynamic						
Q_g	Total Gate Charge[2,3]	V_{DS}=10V,V_{GS}=4.5V, I_D=4A		8.4	12	nC
Q_{gs}	Gate-Source Charge[2,3]			1	2	
Q_{gd}	Gate-Drain Charge[2,3]			2.2	4	
C_{iss}	Input Capacitance	V_{DS}=10V,V_{GS}=0V, f=1MHz		695	1000	pF
C_{oss}	Output Capacitance			45	65	
C_{rss}	Reverse Transfer Capacitance			36	50	
$t_{d(on)}$	Turn-On Time[2,3]	V_{DD}=10V,I_D=1A, V_{GS}=4.5V,R_G=25Ω		4.5	9	ns
t_r				13	25	
$t_{d(off)}$	Turn-Off Time[2,3]			27	51	
t_f				8.3	16	
R_g	Gate Resistance	V_{DS}=0V,V_{GS}=0V, f=1MHz		1.5	3	Ω

Note :
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
3. Essentially independent of operating temperature.

Typical Performance Characteristics

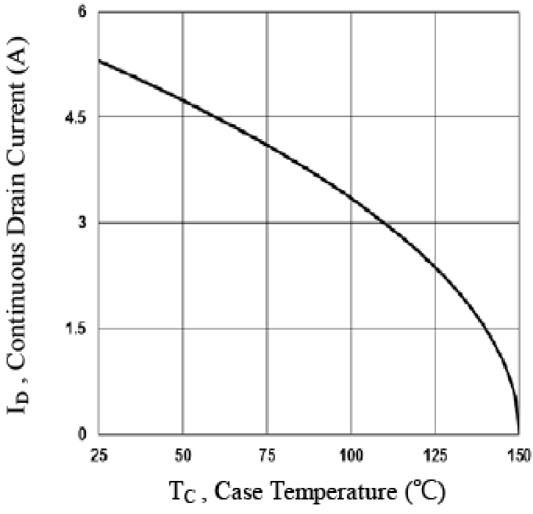


Fig.1 Continuous Drain Current vs. T_c

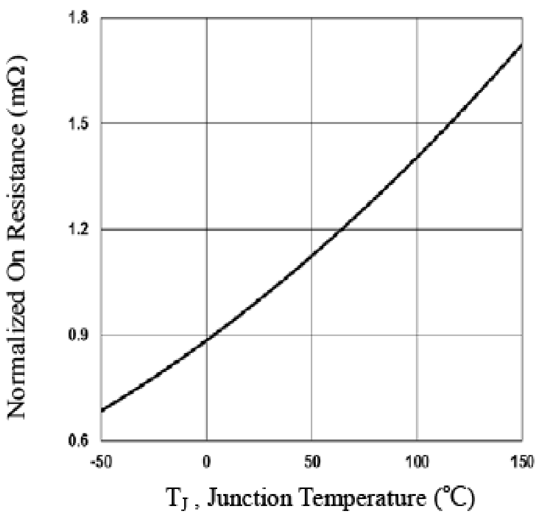


Fig.2 Normalized RDSON vs. T_J

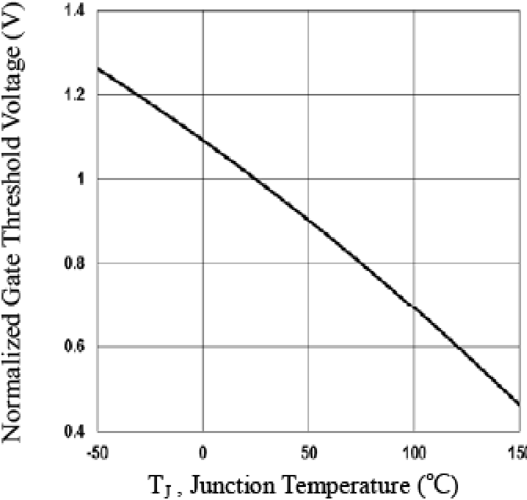


Fig.3 Normalized V_{th} vs. T_J

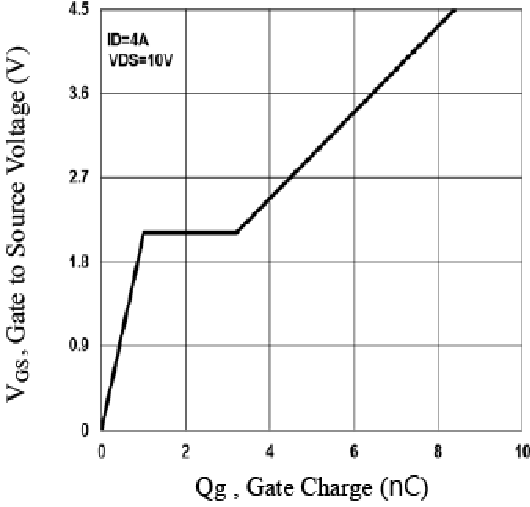


Fig.4 Gate Charge Waveform

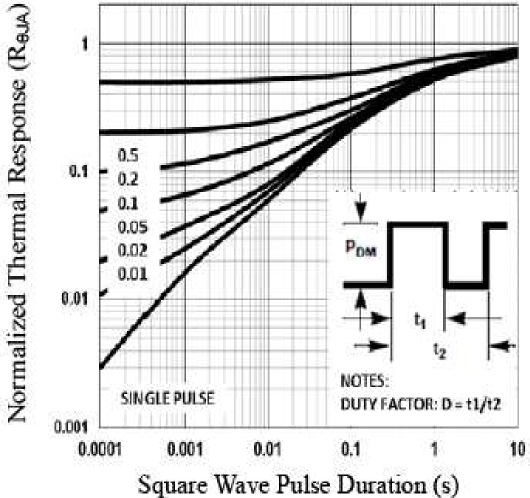


Fig.5 Normalized Transient Impedance

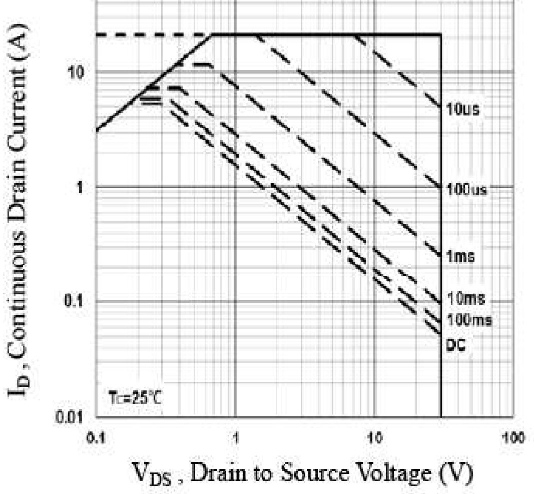
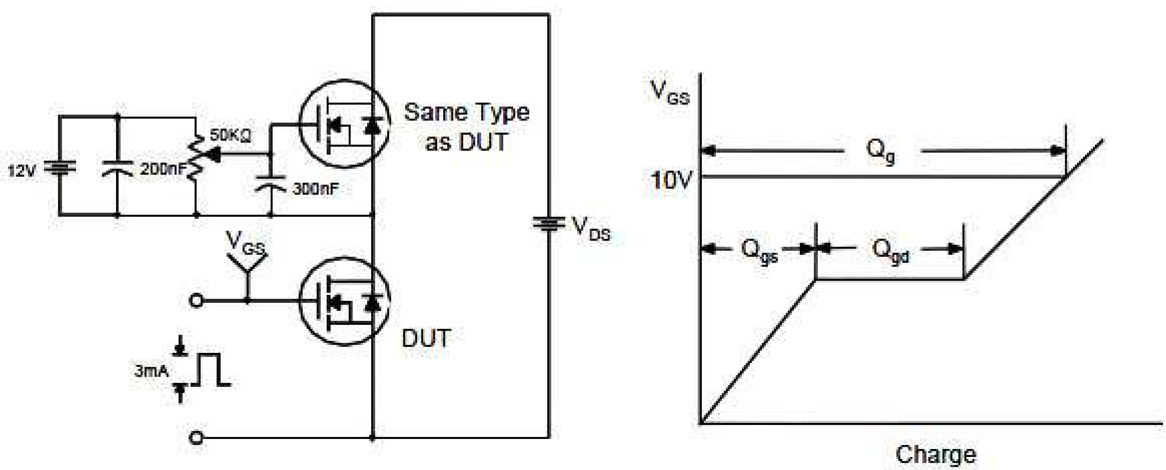


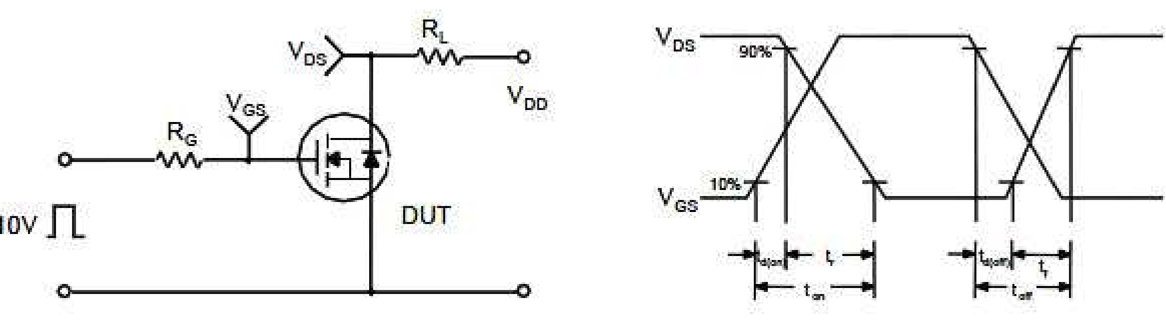
Fig.6 Maximum Safe Operation Area

Typical Performance Characteristics (Continue)

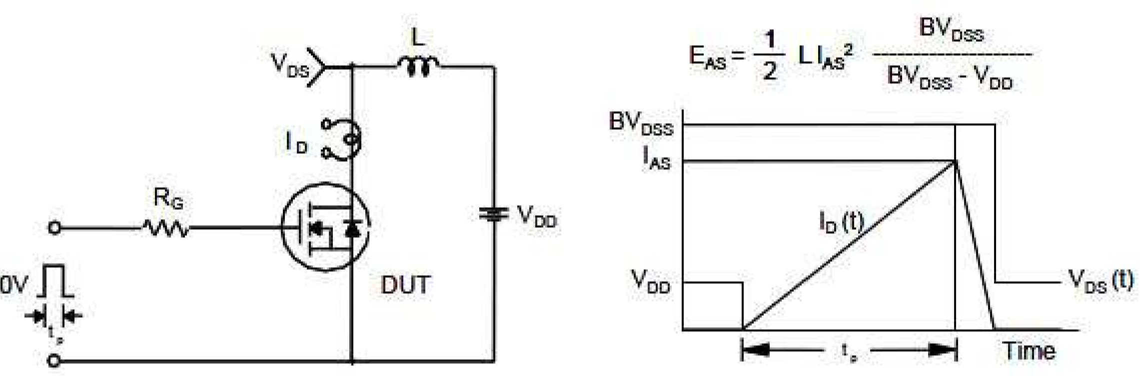
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

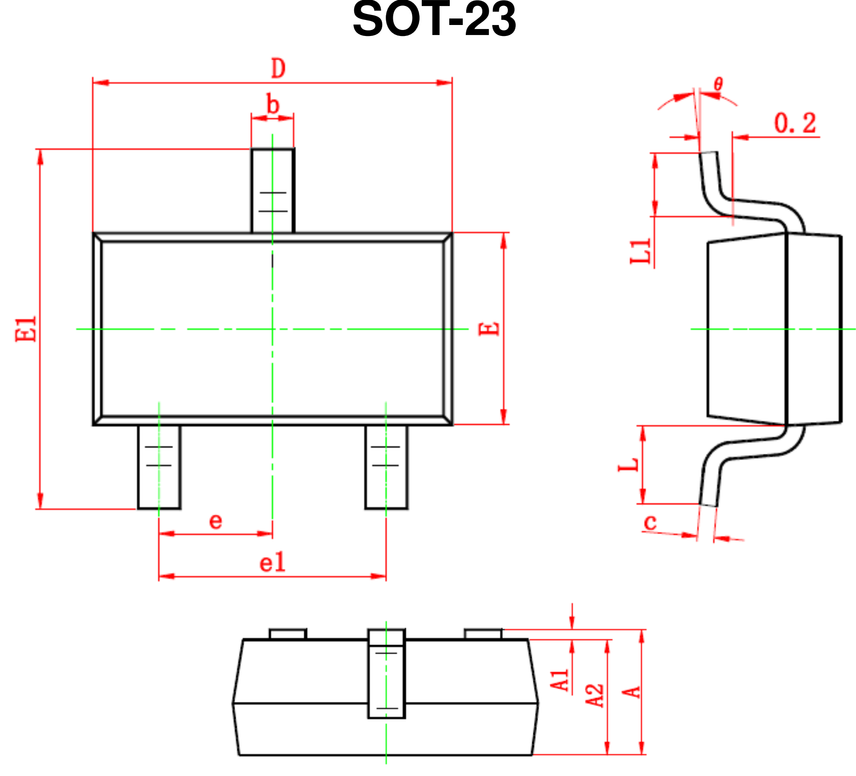


Unclamped Inductive Switching Test Circuit & Waveforms



Package Dimension

SOT-23



Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.200	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0º	8º	0º	6º

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